

**MOSFET Silicon N-Channel MOS**

**1. Applications**

Synchronous rectification in SMPS,  
Hard switching and High speed circuit  
DC/DC in telecoms and industrial



**2. Features**

Low drain-source on-resistance:  $R_{DS(ON)} = 5.6m\Omega$  (typ.)  
High speed power switching  
Enhanced body diode dv/dt capability  
Enhanced avalanche ruggedness



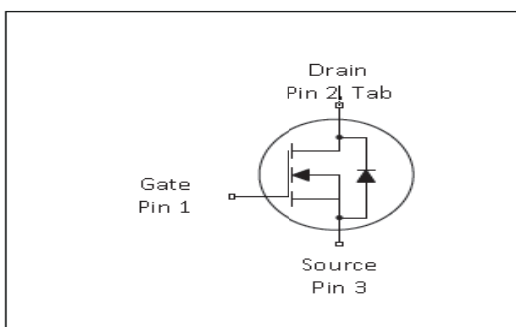
**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	80	V
$R_{DS(on),max}$	6.0	m $\Omega$
$Q_{g,typ}$	55.7	nC
$I_{D,pulse}$	240	A

**3. Packaging and Internal Circuit**

Part Name	Package	Marking
AUA060N08AG	TO220F	AUA060N08AG
AUB060N08AG	TO263	AUB060N08AG
AUP060N08AG	TO220	AUP060N08AG
AUN060N08AG	DFN5x6	AUN060N08AG
AUD060N08AG	TO252	AUD060N08AG

TO220F	TO263	TO220	TO252	DFN5x6



## 1 Maximum ratings

At  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$		-	60	A	$T_C = 25^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-		240	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	300	mJ	
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Power dissipation (TO220F)	$P_{tot}$	-	-	30	W	$T_C = 25^\circ\text{C}$
Power dissipation (TO263&TO220&TO252)	$P_{tot}$	-	-	150	W	$T_C = 25^\circ\text{C}$
Power dissipation (DFN5x6)	$P_{tot}$	-	-	74	W	$T_C = 25^\circ\text{C}$
Storage temperature	$T_{stg}$	-55	-	175	$^\circ\text{C}$	
Operating junction temperature	$T_j$	-55	-	175	$^\circ\text{C}$	

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum Duty Cycle  $D = 0.50$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Identical low side and high side switch with identical  $R_g$

## 2 Thermal characteristics

**Table 3 Thermal characteristics(TO220F)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	5	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	60	°C/W	device on PCB, minimal footprint

**Table Thermal characteristics(TO263&TO220&TO252)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	1	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	62	°C/W	device on PCB, minimal footprint

**Table Thermal characteristics(DFN5x6)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.7	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	50	°C/W	device on PCB, minimal footprint

### 3 Electrical characteristics

at  $T_j=25^{\circ}\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	80	-	-	V	$V_{GS}=0V, I_D=10mA$
Gate threshold voltage	$V_{(GS)th}$	2.5		3.4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	$I_{DSS}$	-	-	1000	nA	$V_{DS}=80V, V_{GS}=0V, T_j=25^{\circ}\text{C}$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	5.4	6.0	m $\Omega$	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Gate resistance (Intrinsic)	$R_G$	-	1.2	-	$\Omega$	$f=1MHz, \text{open drain}$

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	3730	-	pF	$V_{ds}=40V, V_{gs}=0V$ $f=1MHz$
Output capacitance	$C_{oss}$	-	674	-	pF	$V_{ds}=40V, V_{gs}=0V$ $f=1MHz$
Reverse transfer capacitance	$C_{rss}$	-	24.24	-	pF	$V_{ds}=40V, V_{gs}=0V$ $f=1MHz$
Turn-on delay time	$t_{d(on)}$	-	16.5	-	ns	$V_{DD}=40V, V_{GS}=10V, R_G=10\Omega$ $I_D=20A$
Rise time	$t_r$	-	13.7	-	ns	$V_{DD}=40V, V_{GS}=10V, R_G=10\Omega$ $I_D=20A$
Turn-off delay time	$t_{d(off)}$	-	35.9	-	ns	$V_{DD}=40V, V_{GS}=10V, R_G=10\Omega$ $I_D=20A$
Fall time	$t_f$	-	13.45	-	ns	$V_{DD}=40V, V_{GS}=10V, R_G=10\Omega$ $I_D=20A$

**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$	-	15.9	-	nC	$V_{DS}=40V, V_{GS}=0 \text{ to } 10V$ $I_D=20A$
Gate to drain charge	$Q_{gd}$	-	13.3	-	nC	$V_{DS}=40V, V_{GS}=0 \text{ to } 10V$ $I_D=20A$
Gate charge total	$Q_g$	-	55.7	-	nC	$V_{DS}=40V, V_{GS}=0 \text{ to } 10V$ $I_D=20A$

**Table 7 Reverse diode characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.7	-	V	$V_{GS}=0V, I_F=1A, T_J=25^{\circ}C$
Reverse recovery time	$t_{rr}$	-	40.9	-	ns	$V_R=40V, I_F=20A, diF/dt=200A/us$
Reverse recovery charge	$Q_{rr}$	-	106.8	-	uC	$V_R=40V, I_F=20A, diF/dt=200A/us$
Peak reverse recovery current	$I_{rrm}$	-	-3.7	-	A	$V_R=40V, I_F=20A, diF/dt=200A/us$

#### 4 Package Outlines

TO-220F

单位: mm

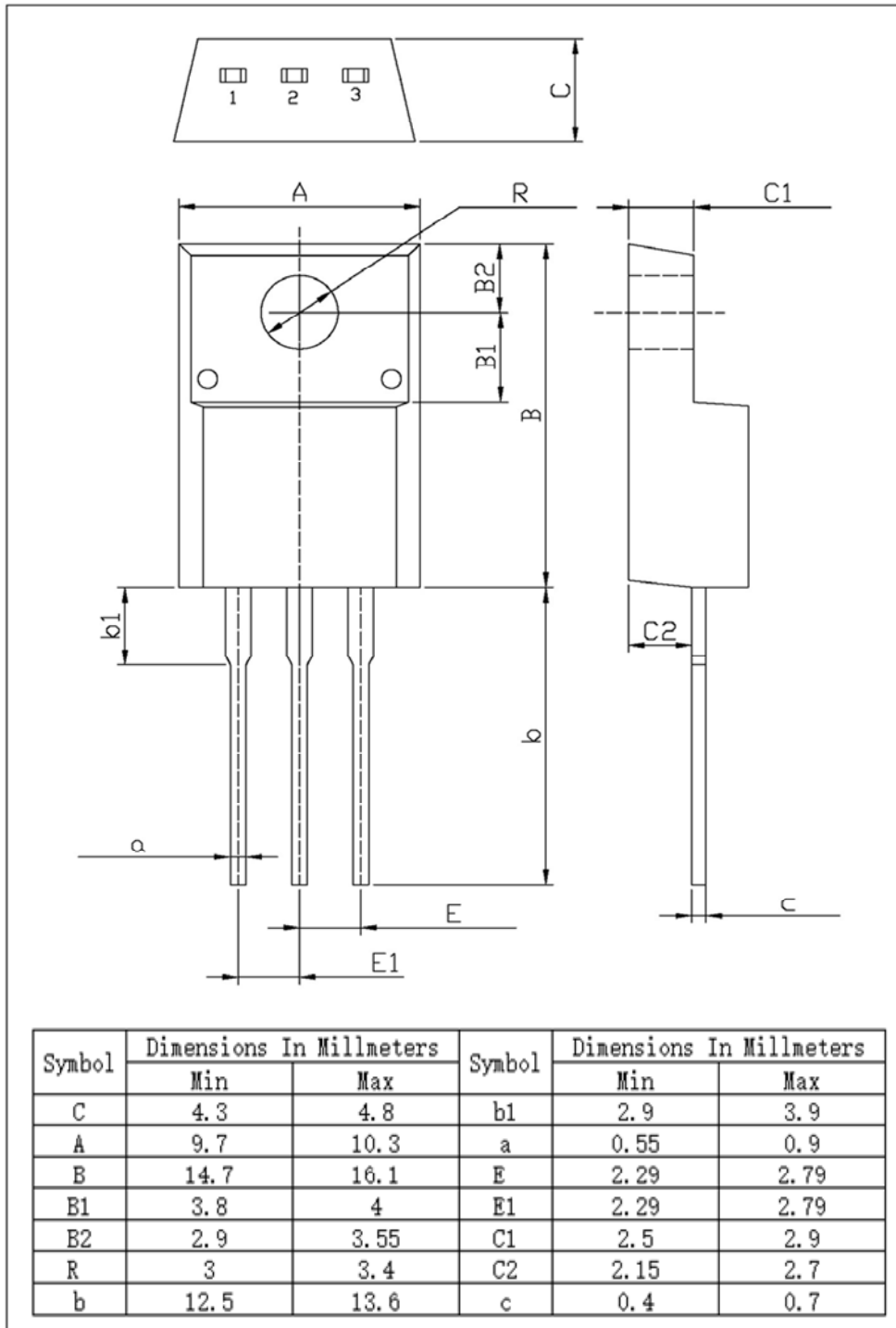


Figure1: Outline PG-TO220F

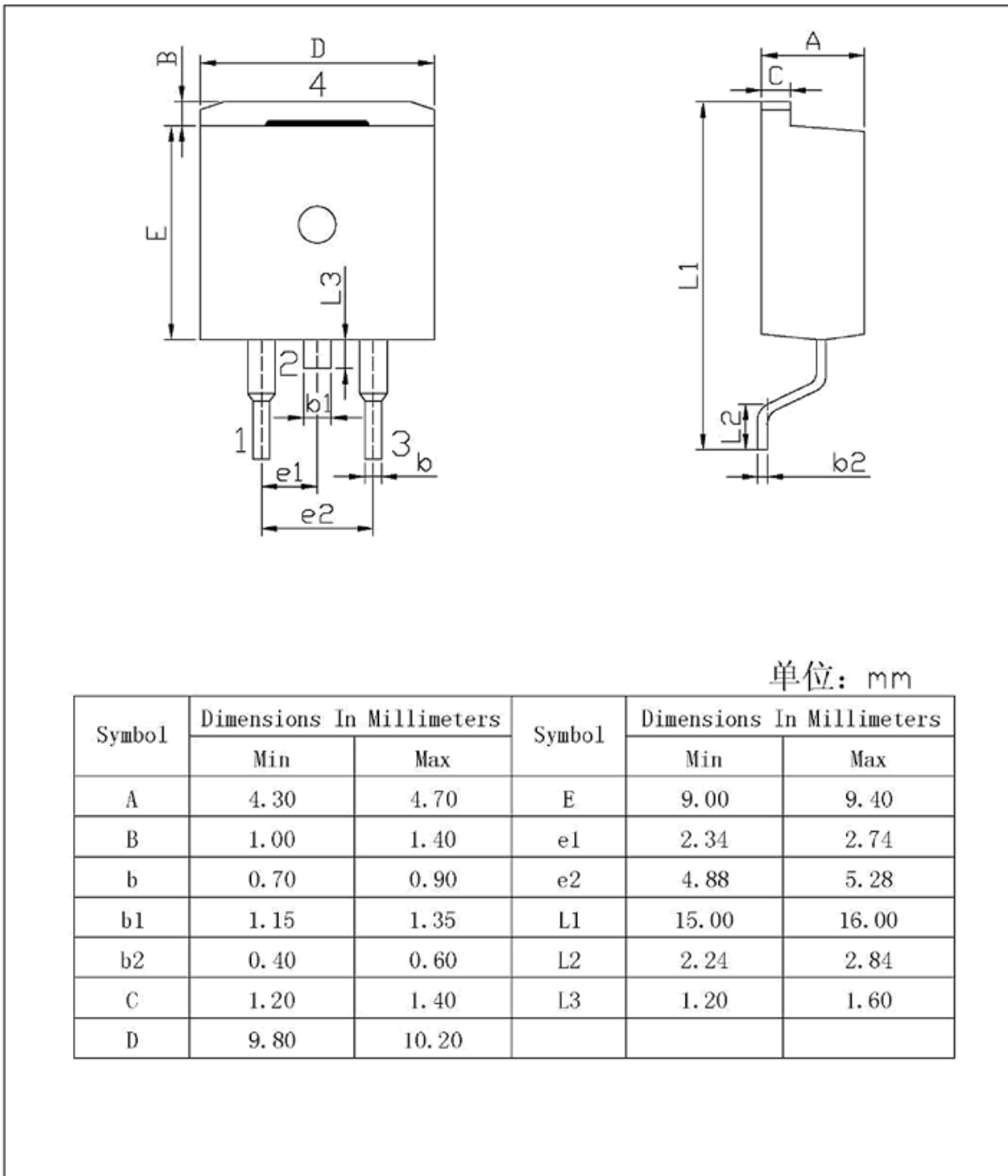
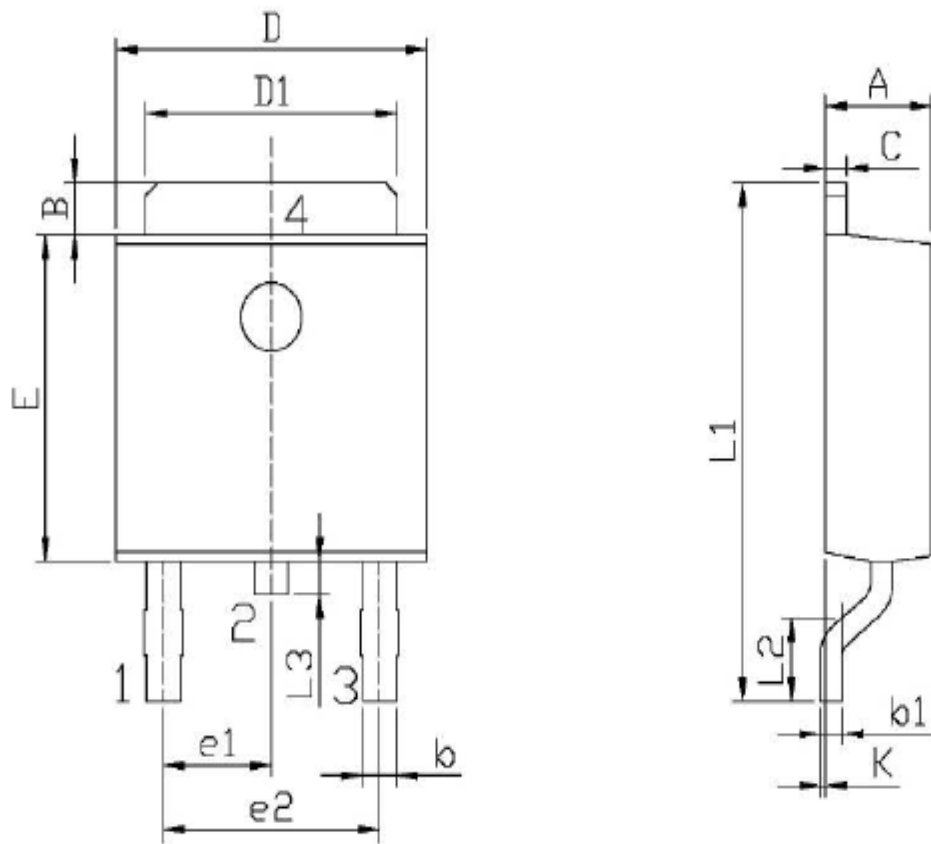


Figure2: Outline PG-T0263



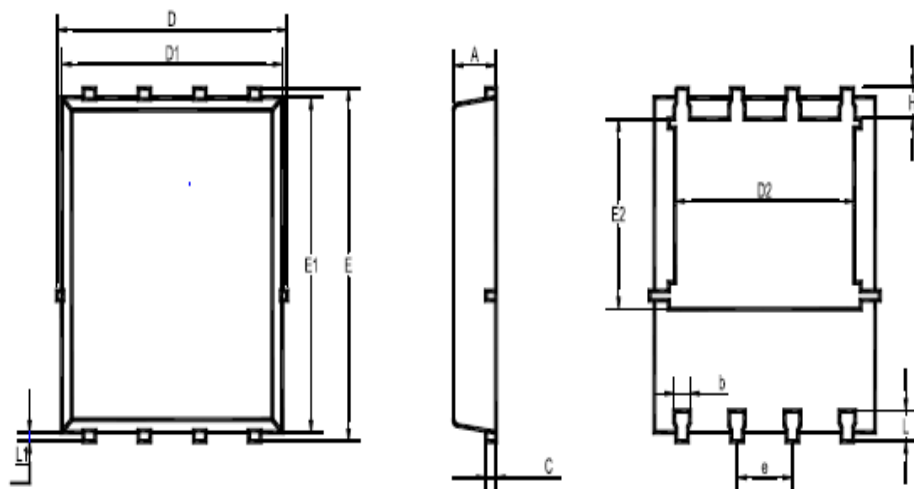




单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

Figure4: OutlinePG-T0252



UNIT	A	b	C	D	D1	D2	E	E1	E2	e	L	L1	H
mm	1.12	0.51	0.34	5.26	5.1	4.5	6.25	6	3.66	1.37	0.71	0.2	0.71
	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35

**Recommended Soldering Footprint**

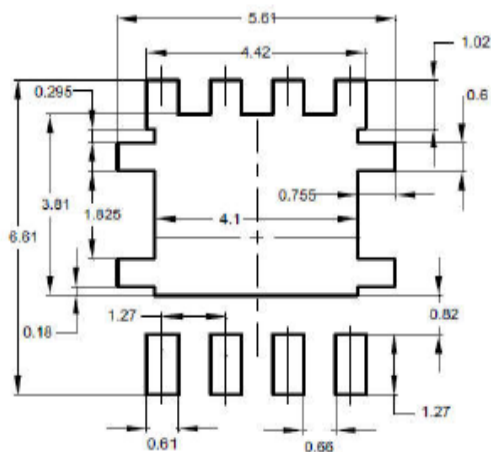


Figure5: Outline PG-DFN5x6

## Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2021-01-21	Preliminary version
1.1	2021-02-04	Add package for TO263&TO220&DFN5x6&TO252

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